

FDC640P

P-Channel 2.5V PowerTrench® Specified MOSFET

General Description

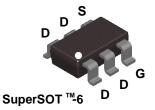
This P-Channel 2.5V specified MOSFET uses a rugged gate version of Fairchild's advanced PowerTrench process. It has been optimized for power management applications with a wide range of gate drive voltage (2.5V – 12V).

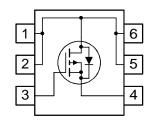
Applications

- Battery management
- Load switch
- Battery protection

Features

- -4.5 A, -20 V $R_{DS(ON)} = 0.053 \Omega @ V_{GS} = -4.5 V$ $R_{DS(ON)} = 0.080 \Omega @ V_{GS} = -2.5 V$
- Rugged gate rating (±12V)
- · Fast switching speed
- High performance trench technology for extremely low $R_{\mbox{\scriptsize DS(ON)}}$





Absolute Maximum Ratings TA=25°C unless otherwise noted

Symbol	l Parameter		Ratings	
V _{DSS}	Drain-Source Voltage		-20	V
V _{GSS}	Gate-Source Voltage		±12	V
I _D	Drain Current - Continuous	(Note 1a)	-4.5	Α
	- Pulsed		-20	
P _D	Maximum Power Dissipation	(Note 1a)	1.6	W
		(Note 1b)	0.8	
T _J , T _{STG}	Operating and Storage Junction Temperature Range		−55 to +150	°C

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	78	°C/W
R _{θJC}	Thermal Resistance, Junction-to-Case	(Note 1)	30	°C/W

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity	
.640	40 FDC640P 7"		8mm	3000 units	

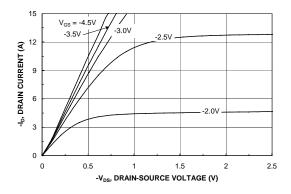
Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Char	acteristics	1	I	I	I	I
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	-20			V
ΔBV _{DSS} ΔT _J	Breakdown Voltage Temperature Coefficient	$I_D = -250 \mu\text{A}$, Referenced to 25°C		-14		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -16 \text{ V}, V_{GS} = 0 \text{ V}$			-1	μΑ
GSSF	Gate-Body Leakage, Forward	$V_{GS} = 12 \text{ V}, \qquad V_{DS} = 0 \text{ V}$			100	nA
I_{GSSR}	Gate-Body Leakage, Reverse	$V_{GS} = -12 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
On Char	acteristics (Note 2)					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	-0.6	-1.0	-1.5	V
$\Delta V_{GS(th)} \over \Delta T_J$	Gate Threshold Voltage Temperature Coefficient	$I_D = -250 \mu\text{A}$, Referenced to 25°C		3		mV/°C
R _{DS(on)}	Static Drain–Source On–Resistance	$V_{GS} = -4.5 \text{ V}, I_D = -4.5 \text{ A}$ $V_{GS} = -2.5 \text{ V}, I_D = -3.6 \text{ A}$ $V_{GS} = -4.5 \text{ V}, I_D = -4.5 \text{ A}, T_J = 125 ^{\circ}\text{C}$		0.039 0.062 0.053	0.053 0.080 0.077	Ω
I _{D(on)}	On-State Drain Current	$V_{GS} = -4.5 \text{ V}, \qquad V_{DS} = -5 \text{ V}$	-20			Α
g Fs	Forward Transconductance	$V_{DS} = -5 \text{ V}, \qquad I_{D} = -4.5 \text{ A}$		16		S
Dvnamio	Characteristics					
C _{iss}	Input Capacitance	$V_{DS} = -10 \text{ V}, \qquad V_{GS} = 0 \text{ V},$		890		pF
C _{oss}	Output Capacitance	f = 1.0 MHz		244		pF
C _{rss}	Reverse Transfer Capacitance	7		123		pF
Switchir	g Characteristics (Note 2)			•	•	
t _{d(on)}	Turn-On Delay Time	$V_{DD} = -10 \text{ V}, \qquad I_{D} = -1 \text{ A},$		12	22	ns
t _r	Turn-On Rise Time	$V_{GS} = -4.5 \text{ V}, \qquad R_{GEN} = 6 \Omega$		9	18	ns
d(off)	Turn-Off Delay Time			24	38	ns
t _f	Turn-Off Fall Time			13	23	ns
Qg	Total Gate Charge	$V_{DS} = -10 \text{ V}, \qquad I_{D} = -4.5 \text{ A},$		9	13	nC
Q _{gs}	Gate-Source Charge	$V_{GS} = -4.5 \text{ V}$		2		nC
Q_{gd}	Gate-Drain Charge			3		nC
Drain-S	ource Diode Characteristics	and Maximum Ratings				
I _S	Maximum Continuous Drain-Source				-1.3	Α
V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = -1.3 \text{ A} \text{(Note 2)}$		-0.7	-1.2	V

Notes

- a. 78°C/W when mounted on a 1in² pad of 2oz copper on FR-4 board.
- b. 156°C/W when mounted on a minimum pad.
- 2. Pulse Test: Pulse Width $\leq 300~\mu s,~Duty~Cycle \leq 2.0\%$

^{1.} $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.

Typical Characteristics



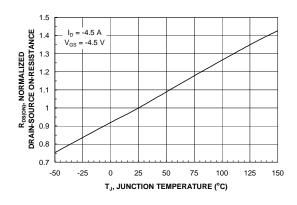
OBAIN-SOURCE ON RESISTANCE

OBAIN-SOURCE

OB

Figure 1. On-Region Characteristics.

Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.



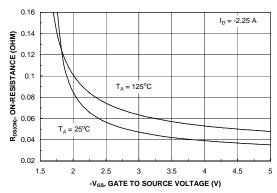
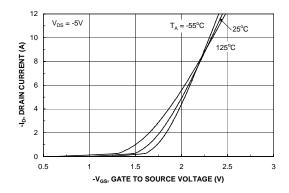


Figure 3. On-Resistance Variation with Temperature.

Figure 4. On-Resistance Variation with Gate-to-Source Voltage.



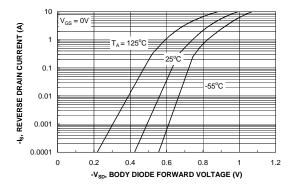
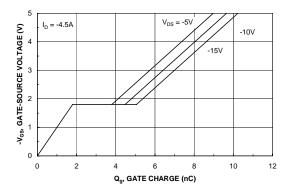


Figure 5. Transfer Characteristics.

Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics



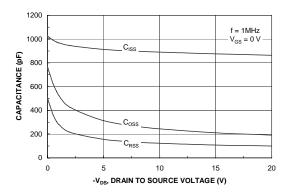
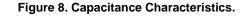
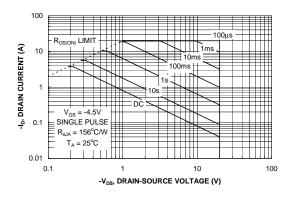


Figure 7. Gate Charge Characteristics.





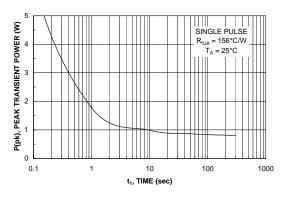


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

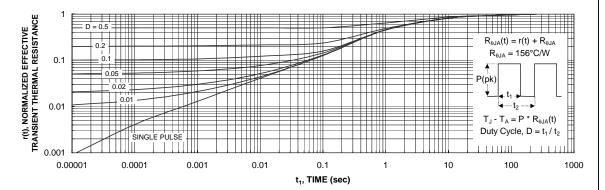


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1b Transient thermal response will change depending on the circuit board design.

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